Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK2967

DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 48 m Ω (typ.)

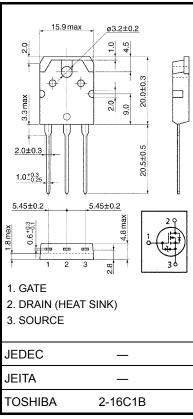
• High forward transfer admittance $: |Y_{fs}| = 30 \text{ S (typ.)}$

• Low leakage current $: I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 250 \text{ V)}$

• Enhancement mode : $V_{th} = 1.5 \sim 3.5 \text{ V (VDS} = 10 \text{ V, ID} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	250	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	250	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	ΙD	30	Α	
	Pulse (Note 1)	I _{DP}	120	Α	
Drain power dissipation	n (Tc = 25°C)	P_{D}	150	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	925	mJ	
Avalanche current		I _{AR}	30	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 1.74 mH, I_{AR} = 30 A, R_G = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device.

Please handle with caution.



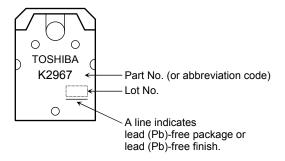
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 250 V, V _{GS} = 0 V	-	_	100	μΑ
Drain-source br voltage	eakdown	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	250	_	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.5	_	3.5	V
Drain-source Ol	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 15 A		48	68	mΩ
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 15 A	15	30	_	S
Input capacitano	e	C _{iss}			5400	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		580	_	
Output capacitance		Coss	1		1900	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{\underset{OV}{\text{OV}}} \stackrel{I_{D}=15A}{\underset{R_{L}=}{\text{OVOUT}}} V_{DD} \stackrel{=}{\Rightarrow} 100V$	_	20	_	
	Turn-on time	t _{on}		-	50	_	
	Fall time	t _f		_	35	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{w}} = 10 \mu s$	-	200	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	132	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		80		nC
Gate-drain ("miller") Charge		Q _{gd}			52	_	

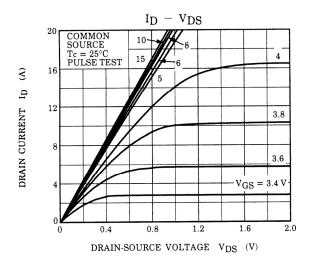
Source-Drain Ratings and Characteristics (Ta = 25°C)

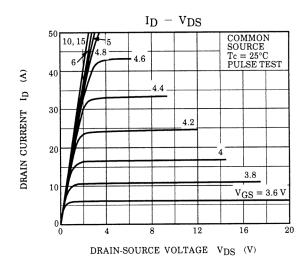
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	-	_	30	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	120	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 30 A, V _{GS} = 0 V	ı	_	-2.0	V
Reverse recovery time	t _{rr}	I _{DR} = 30 A, V _{GS} = 0 V	l	270	1	ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 100 A / μs	_	3.0	_	μC

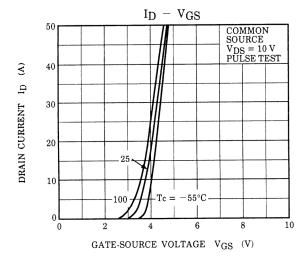
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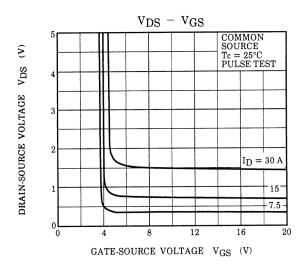


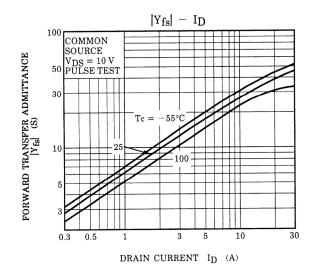
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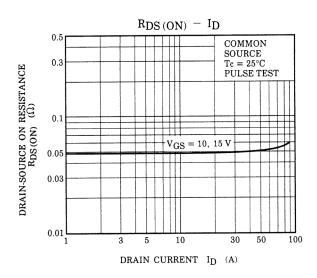


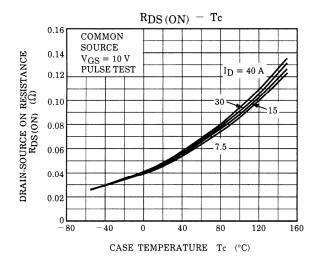


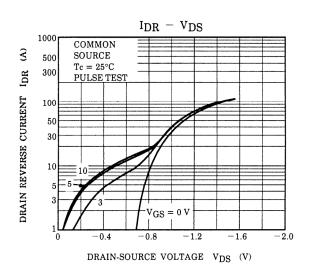


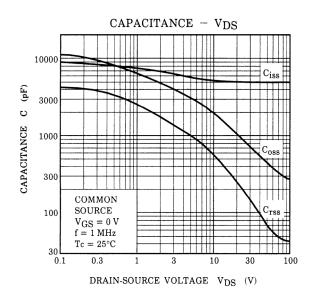


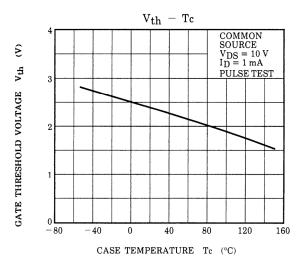


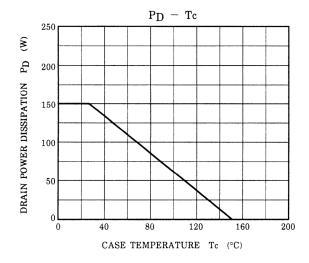


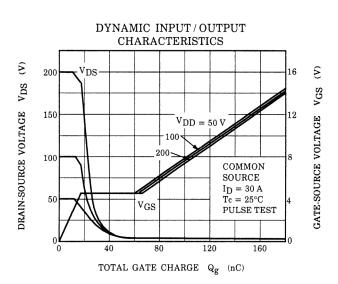


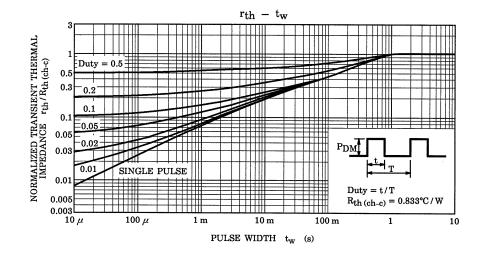


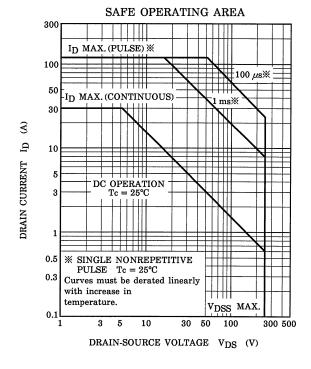


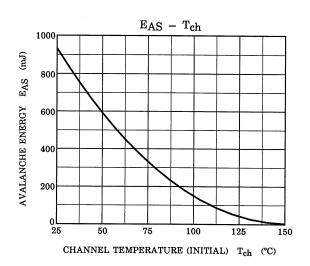


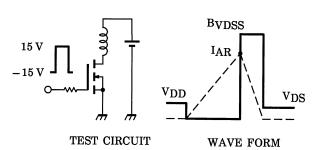












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 50~V,~L = 1.74~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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